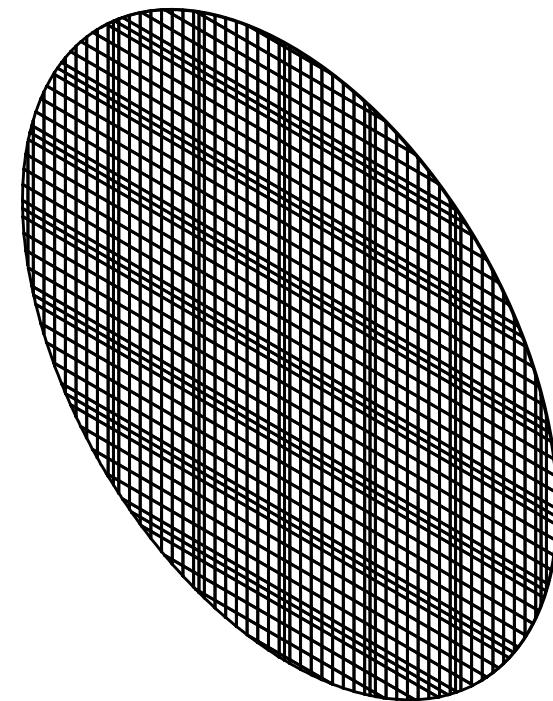
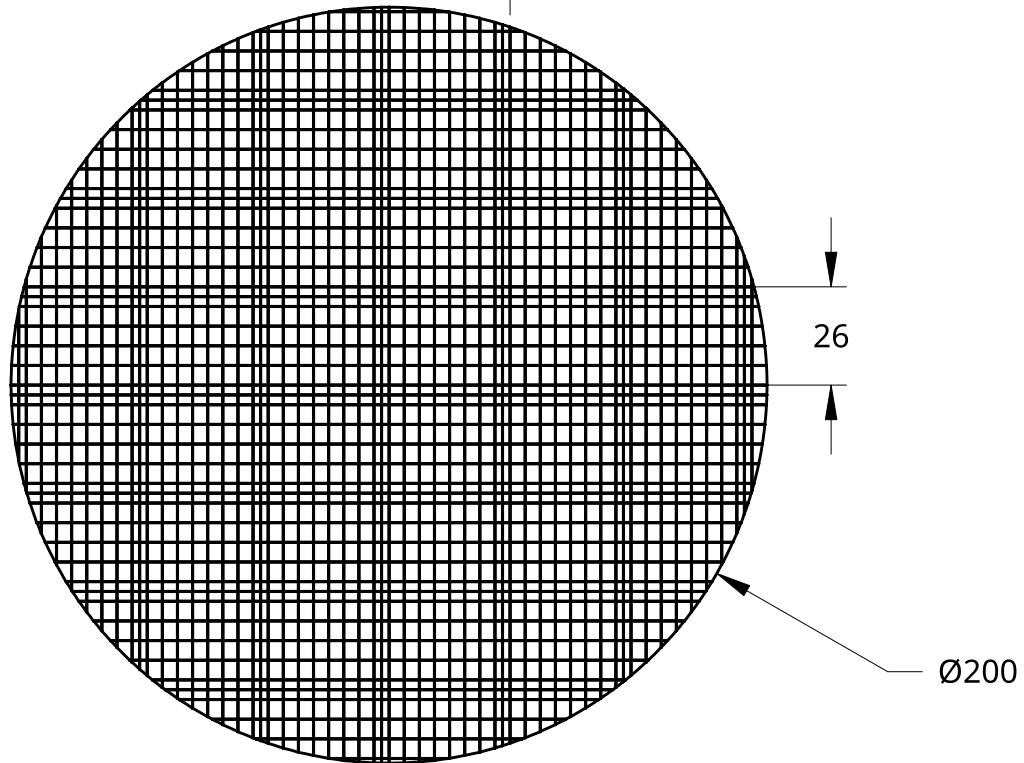


2

1

Reticle Size: 32mm x 26mm
 Wafer Size: 200mm



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UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS			NAME	DATE			
ANGULAR = \pm °		DRAWN	ANDREW WINGATE	09/21/2025			
SURFACE FINISH ✓		CHECKED			TITLE		
DO NOT SCALE DRAWING		APPROVED			wafer.space Wafer Dicing Schema Run 1 GF180MCU		
BREAK ALL SHARP EDGES AND REMOVE BURRS					SIZE	DWG NO.	
THIRD ANGLE PROJECTION		MATERIAL	FINISH		A		REV. 2
				SCALE 1:2	WEIGHT		SHEET 1 of 7

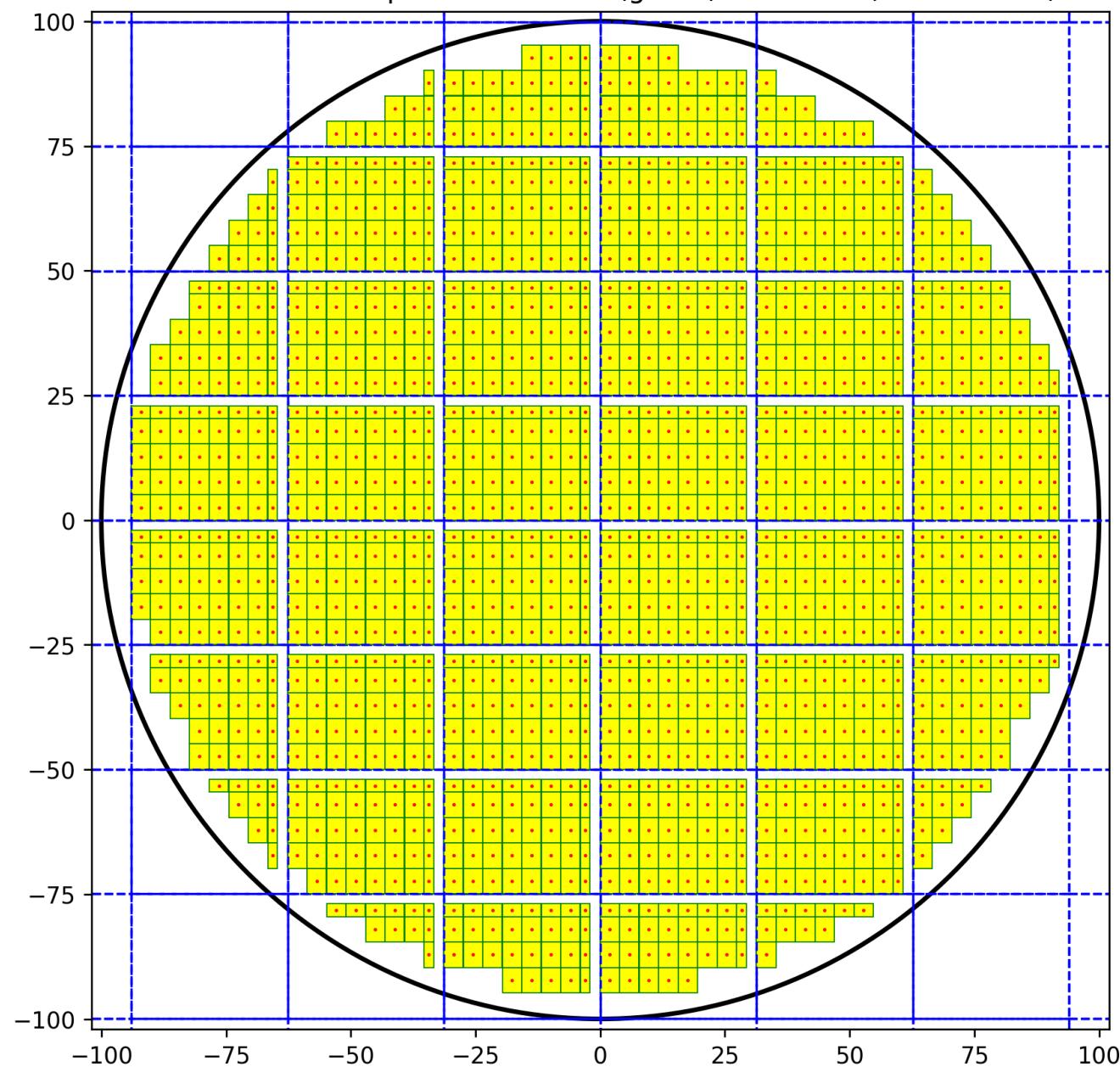
2

1

2

1

200mm Wafer Map: 1934 full dies (green) + reticles (blue dashed)



2

1

B

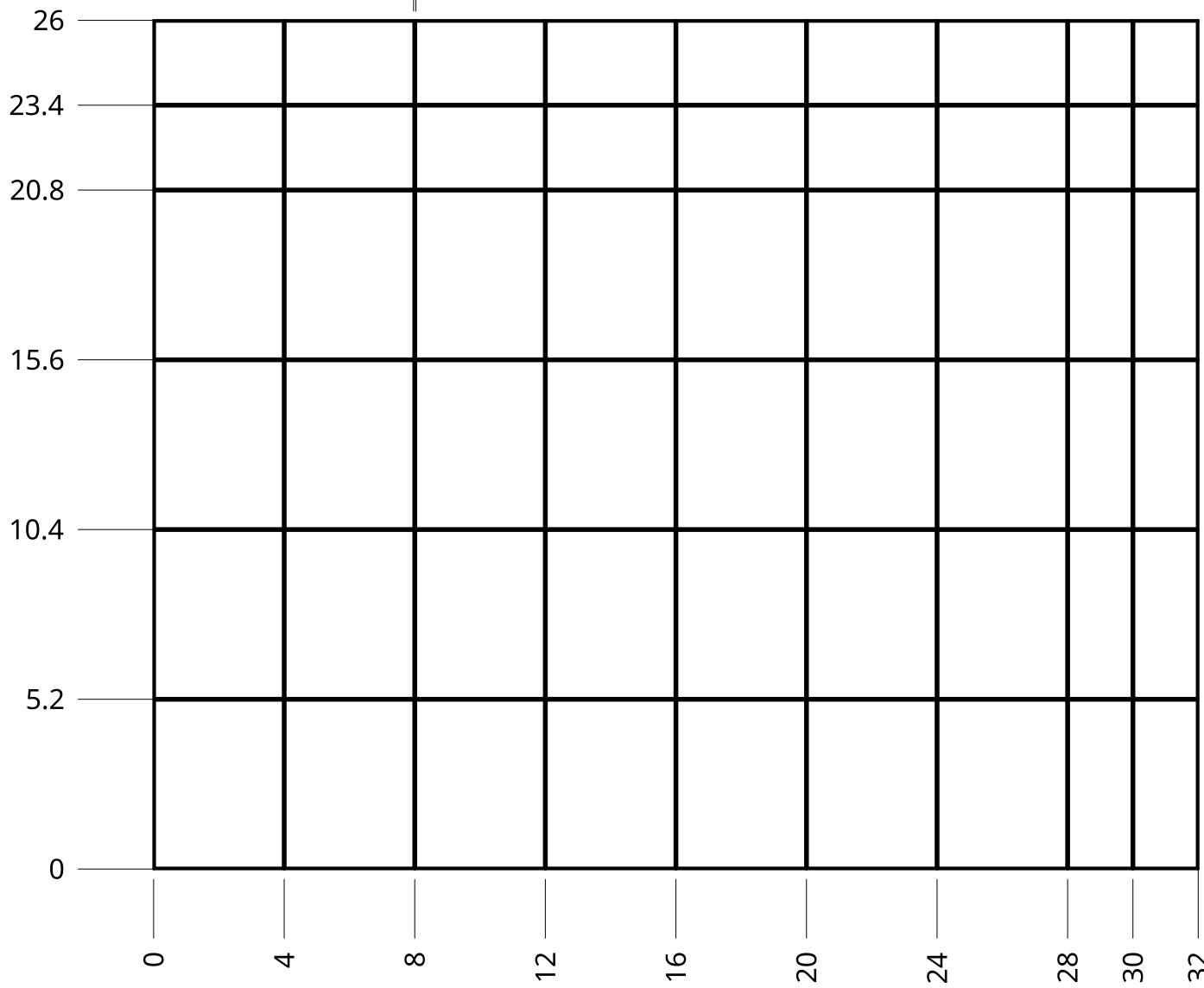
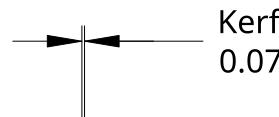
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2

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2

1



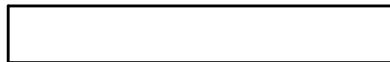
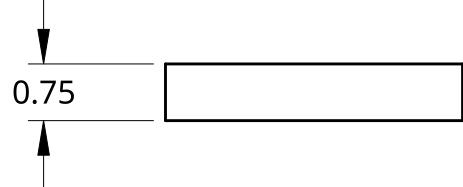
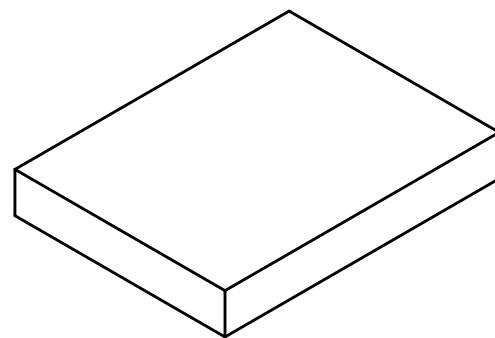
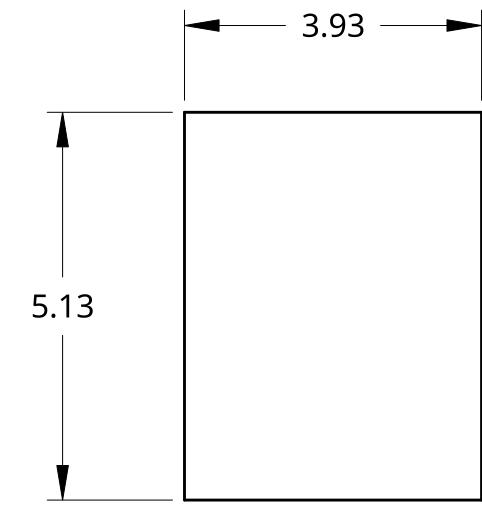
Note: Dimensions are cut centerlines

Note: Kerf = .07mm

2

1

B



B

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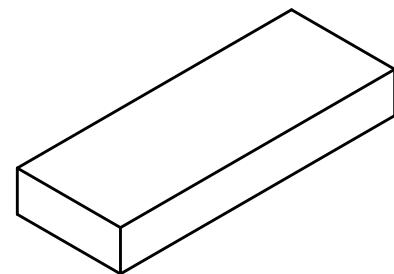
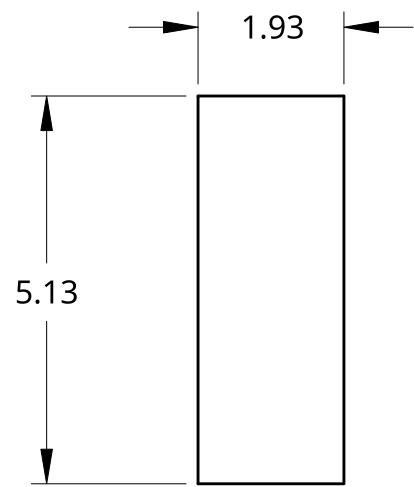
2

1

2

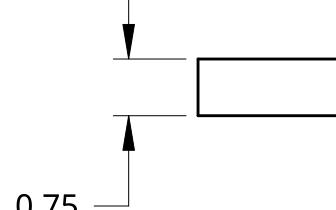
1

B



B

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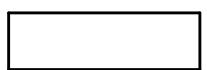
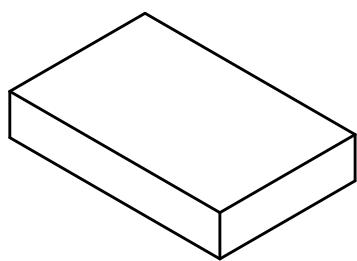
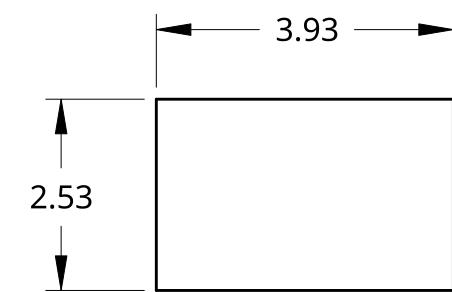


A

2

1

B



0.75

A

B

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2

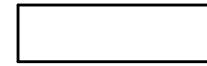
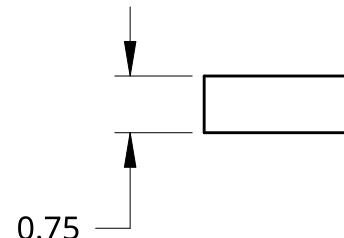
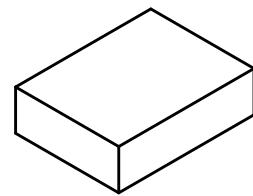
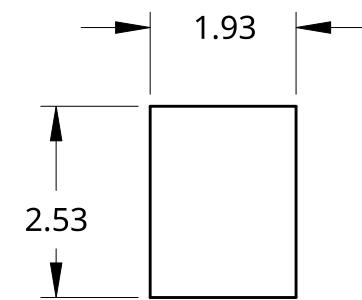
1

2

1

B

B



A

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